

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAB75N03U
Package Type :	PDFNWB3.3x3.3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Die	Silicon	7440-21-3	100.00%	1.3823%
Lead Frame	Copper	7440-50-8	97.685%	22.821%
	Iron	7439-89-6	2.10%	
	Phosphorus	7723-14-0	0.015%	
	Zinc	7440-66-6	0.10%	
	Sliver	7440-22-4	0.10%	
Solder paste	Pb	7439-92-1	88.50%	2.1416%
	Sn	7440-31-5	2.50%	
	Rosin, hydrogenated	65997-06-0	3.00%	
	Ag	7440-22-4	1.50%	
	Terpineol	8000-41-7	1.50%	
	2-(2-butoxyethos)ethanol	112-34-5	2.50%	
	Amines	61791-63-7	0.50%	2.1416%
	Pb	7439-92-1	88.00%	
	Sn	7440-31-5	2.50%	
	Rois,hydrogenated	65997-06-0	2.00%	
	silver	7440-22-4	2.00%	
	Terpineol	8000-41-7	2.50%	
	2-(2-butoxyethos)ethanol	112-34-5	2.50%	
	Amines	61791-63-7	0.50%	
Bond Wire	Au	7440-57-5	99.99%	0.0584%
	others	/	0.01%	
Clip Bond	Cu	7440-50-8	97.45%	33.5337%
	Fe	7439-89-6	2.30%	
	P	7723-14-0	0.10%	
	Zn	7440-66-6	0.15%	
Mold Compound	Epoxy Resin	Trade secret	5.00%	35.9532%
	Phenol Resin	Trade secret	2.00%	
	Silica(Amorphous) A	60676-86-0	80.50%	
	Silica(Amorphous) B	7631-86-9	12.00%	
	Carbon Black	1333-86-4	0.50%	
Solder Plating	Sn	7440-31-5	99.99%	1.9682%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.